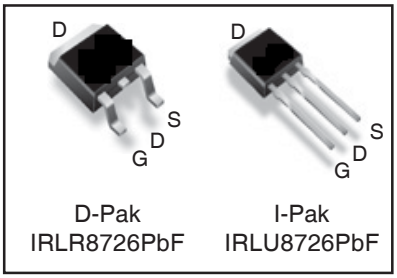
IRLR8726TRPBF

® Power MOSFET

V_{DSS}	$R_{DS(on)}$ max	Qg (typ.)
30V	5.8mΩ@V_{GS} = 10V	15nC



D-Pak
IRLR8726PbF

I-Pak
IRLU8726PbF

Applications

- High Frequency Synchronous Buck Converters for Computer Processor Power
- High Frequency Isolated DC-DC Converters with Synchronous Rectification for Telecom and Industrial Use

Benefits

- Very Low $R_{DS(on)}$ at 4.5V V_{GS}
- Ultra-Low Gate Impedance
- Fully Characterized Avalanche Voltage and Current
- Lead-Free
- RoHS compliant

G	D	S
Gate	Drain	Source

Absolute Maximum Ratings

	Parameter	Max.	Units
V_{DS}	Drain-to-Source Voltage	30	V
V_{GS}	Gate-to-Source Voltage	± 20	
I_D @ T_C = 25°C	Continuous Drain Current, V_{GS} @ 10V	86④	A
I_D @ T_C = 100°C	Continuous Drain Current, V_{GS} @ 10V	61④	
I_{DM}	Pulsed Drain Current ①	340	
P_D @T_C = 25°C	Maximum Power Dissipation ⑥	75	W
P_D @T_C = 100°C	Maximum Power Dissipation ⑥	38	
	Linear Derating Factor	0.5	W/°C
T_J T_{STG}	Operating Junction and Storage Temperature Range	-55 to + 175	°C
	Soldering Temperature, for 10 seconds	300 (1.6mm from case)	

Thermal Resistance

	Parameter	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case ⑥	—	2.0	°C/W
$R_{\theta JA}$	Junction-to-Ambient (PCB Mount) ⑤⑥	—	50	
$R_{\theta JA}$	Junction-to-Ambient ⑥	—	110	

Notes ① through ⑥ are on page 11

Static @ T_J = 25°C (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
BV_{DSS}	Drain-to-Source Breakdown Voltage	30	—	—	V	V_{GS} = 0V, I_D = 250µA
$\Delta BV_{DSS}/\Delta T_J$	Breakdown Voltage Temp. Coefficient	—	20	—	mV/°C	Reference to 25°C, I_D = 1mA
$R_{DS(on)}$	Static Drain-to-Source On-Resistance	—	4.0	5.8	mΩ	V_{GS} = 10V, I_D = 25A ③
		—	5.8	8.0		V_{GS} = 4.5V, I_D = 20A ③
$V_{GS(th)}$	Gate Threshold Voltage	1.35	1.80	2.35	V	V_{DS} = V_{GS}, I_D = 50µA
$\Delta V_{GS(th)}/\Delta T_J$	Gate Threshold Voltage Coefficient	—	-8.6	—	mV/°C	
I_{DSS}	Drain-to-Source Leakage Current	—	—	1.0	µA	V_{DS} = 24V, V_{GS} = 0V
		—	—	150		V_{DS} = 24V, V_{GS} = 0V, T_J = 125°C
I_{GSS}	Gate-to-Source Forward Leakage	—	—	100	nA	V_{GS} = 20V
	Gate-to-Source Reverse Leakage	—	—	-100		V_{GS} = -20V
gfs	Forward Transconductance	73	—	—	S	V_{DS} = 15V, I_D = 20A
Q_g	Total Gate Charge	—	15	23		
Q_{gs1}	Pre-Vth Gate-to-Source Charge	—	3.7	—		V_{DS} = 15V
Q_{gs2}	Post-Vth Gate-to-Source Charge	—	1.9	—	nC	V_{GS} = 4.5V
Q_{gd}	Gate-to-Drain Charge	—	5.7	—		I_D = 20A
Q_{godr}	Gate Charge Overdrive	—	3.7	—		See Fig. 15
Q_{sw}	Switch Charge (Q_{gs2} + Q_{gd})	—	7.6	—		
Q_{oss}	Output Charge	—	10	—	nC	V_{DS} = 15V, V_{GS} = 0V
R_G	Gate Resistance	—	2.0	3.5	Ω	
$t_{d(on)}$	Turn-On Delay Time	—	12	—		V_{DD} = 15V, V_{GS} = 4.5V③
t_r	Rise Time	—	49	—		I_D = 20A
$t_{d(off)}$	Turn-Off Delay Time	—	15	—	ns	R_G = 1.8Ω
t_f	Fall Time	—	16	—		See Fig. 13
C_{iss}	Input Capacitance	—	2150	—		V_{GS} = 0V
C_{oss}	Output Capacitance	—	480	—	pF	V_{DS} = 15V
C_{rss}	Reverse Transfer Capacitance	—	205	—		f = 1.0MHz

Avalanche Characteristics

	Parameter	Typ.	Max.	Units
E_{AS}	Single Pulse Avalanche Energy②	—	120	mJ
I_{AR}	Avalanche Current ①	—	20	A

Diode Characteristics

	Parameter	Min.	Typ.	Max.	Units	Conditions
I_S	Continuous Source Current (Body Diode)	—	—	86④	A	MOSFET symbol showing the integral reverse p-n junction diode.
I_{SM}	Pulsed Source Current (Body Diode) ①	—	—	340		
V_{SD}	Diode Forward Voltage	—	—	1.0	V	T_J = 25°C, I_S = 20A, V_{GS} = 0V ③
t_{rr}	Reverse Recovery Time	—	24	36	ns	T_J = 25°C, I_F = 20A, V_{DD} = 15V
Q_{rr}	Reverse Recovery Charge	—	52	78	nC	di/dt = 300A/µs ③

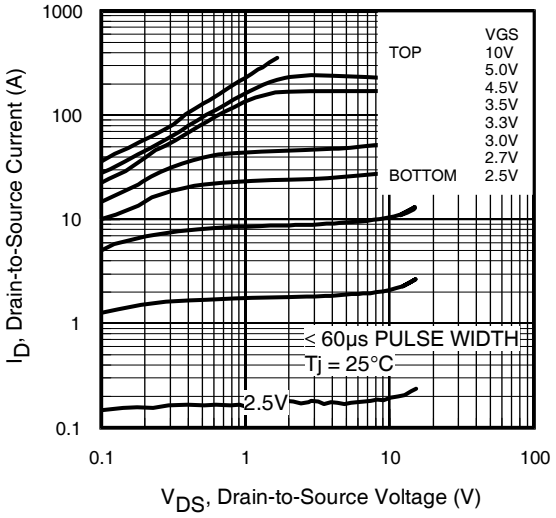


Fig 1. Typical Output Characteristics

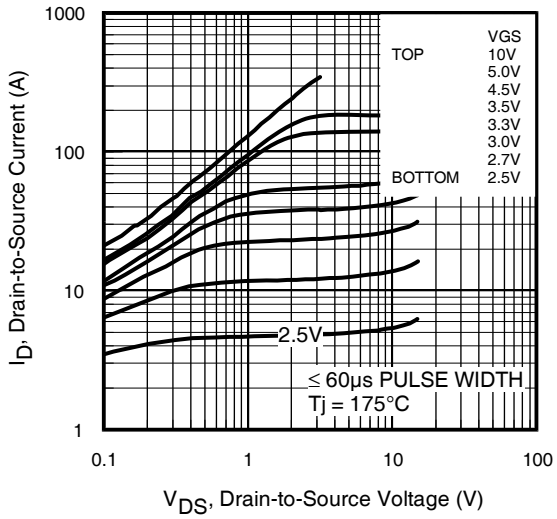


Fig 2. Typical Output Characteristics

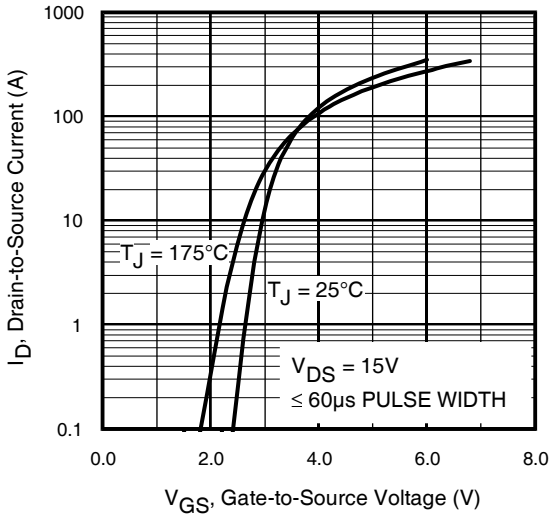


Fig 3. Typical Transfer Characteristics

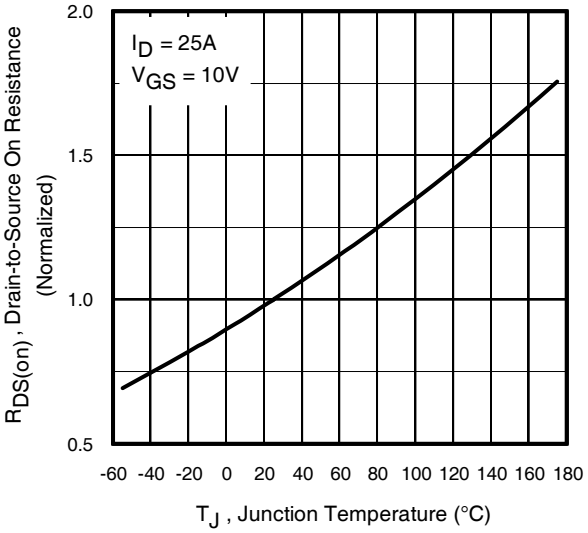


Fig 4. Normalized On-Resistance vs. Temperature

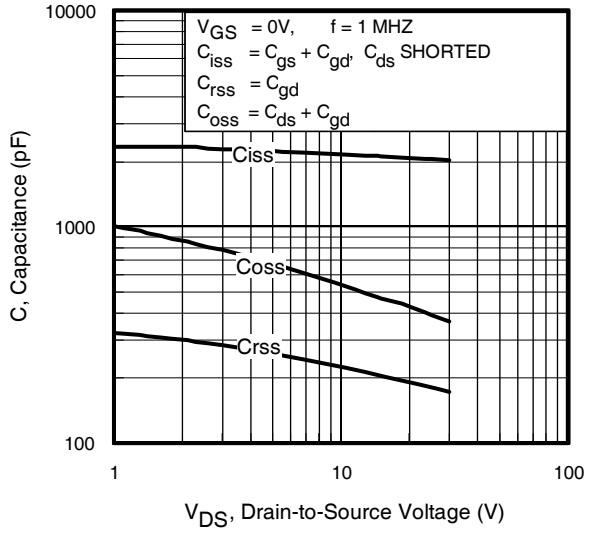


Fig 5. Typical Capacitance vs. Drain-to-Source Voltage

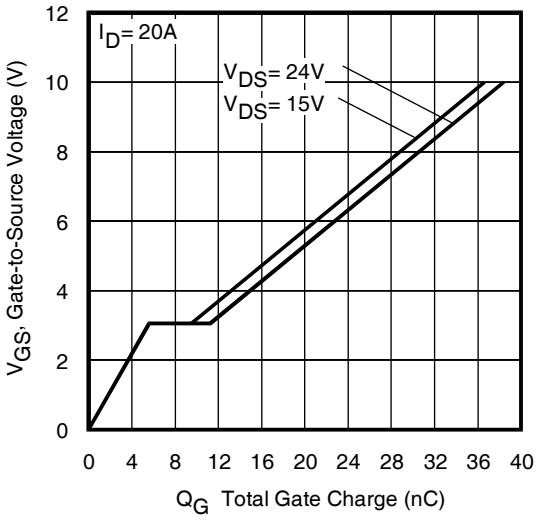


Fig 6. Typical Gate Charge vs. Gate-to-Source Voltage

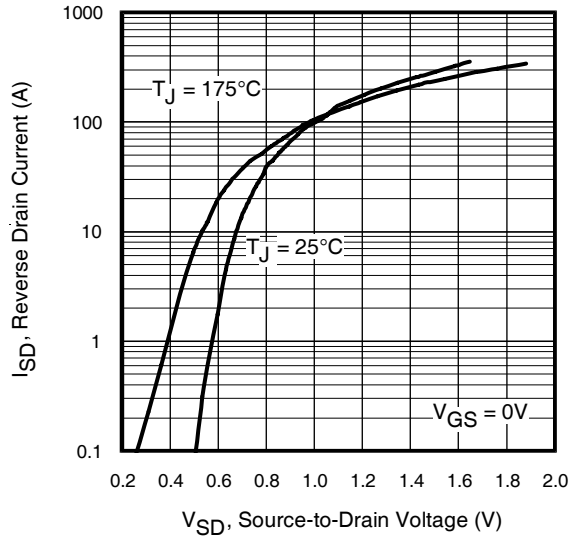


Fig 7. Typical Source-Drain Diode Forward Voltage

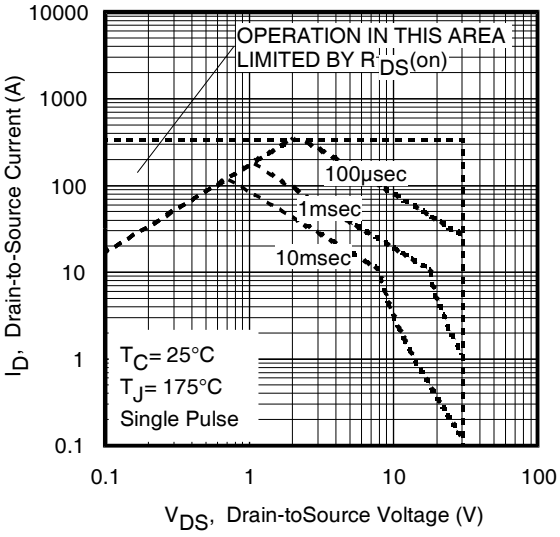


Fig 8. Maximum Safe Operating Area

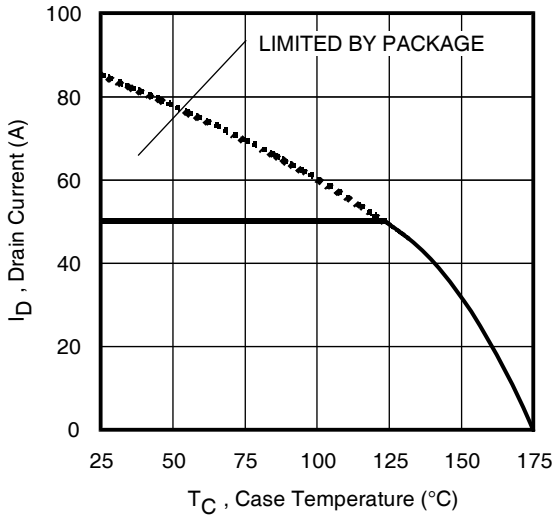


Fig 9. Maximum Drain Current vs. Case Temperature

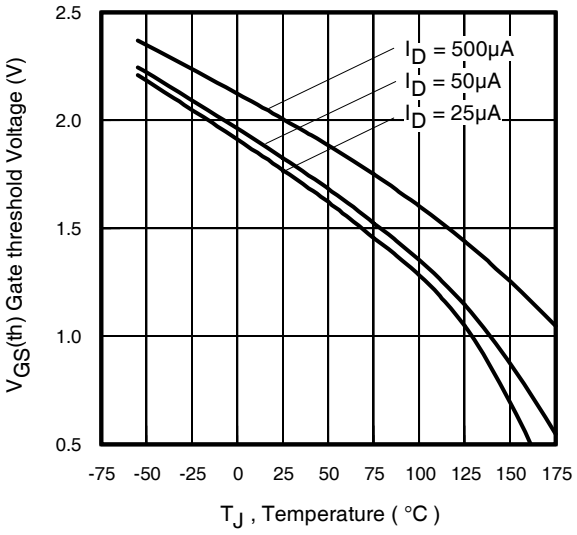


Fig 10. Threshold Voltage vs. Temperature

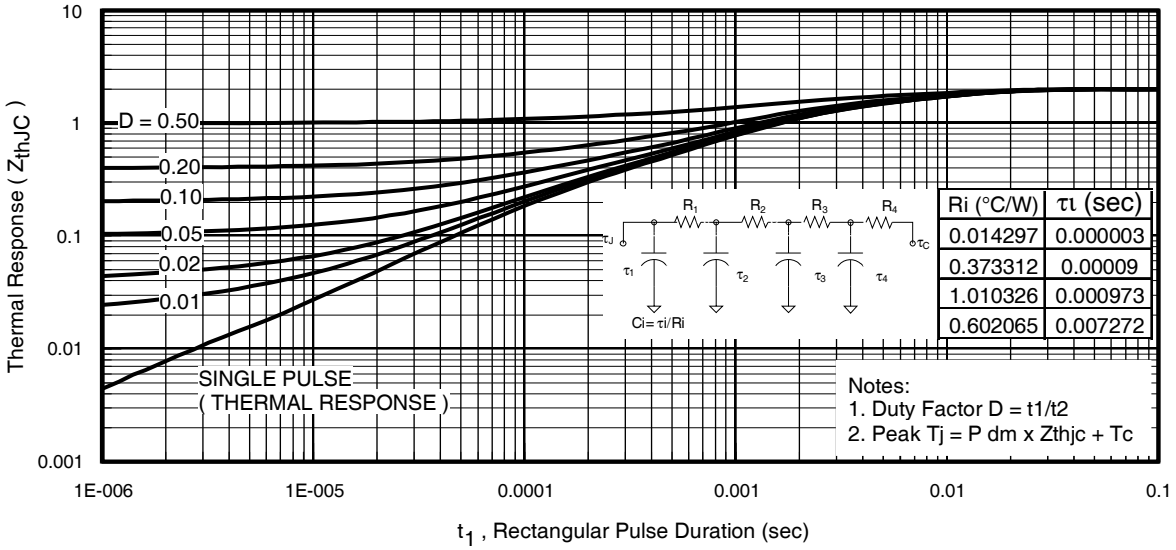


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Case

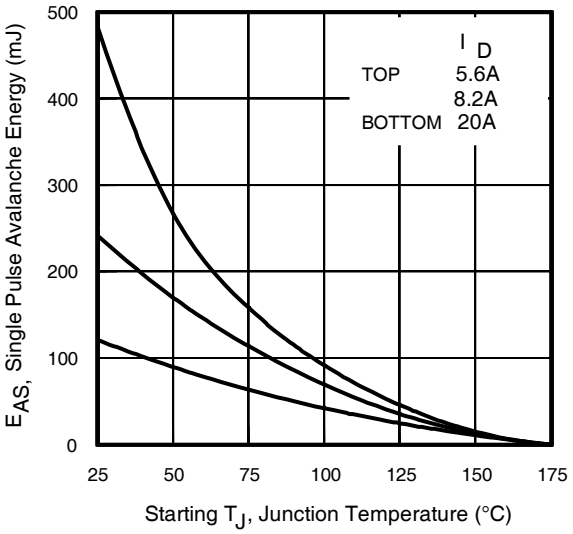


Fig 12a. Maximum Avalanche Energy
Vs. Drain Current

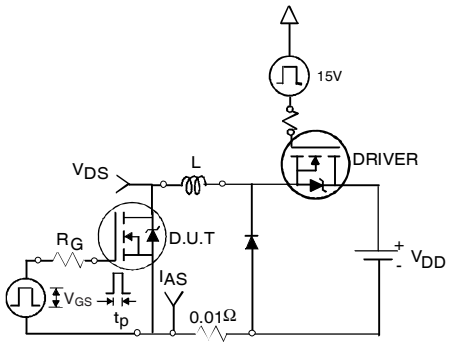


Fig 12b. Unclamped Inductive Test Circuit

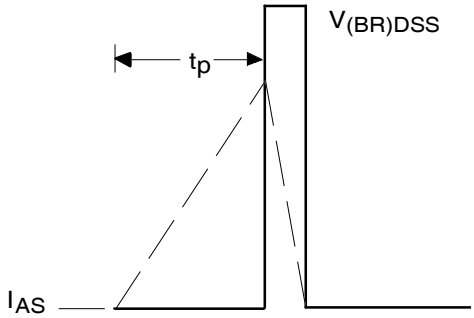


Fig 12c. Unclamped Inductive Waveforms

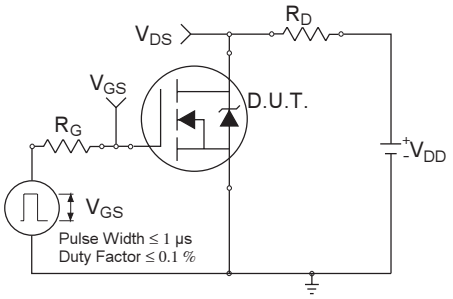


Fig 13a. Switching Time Test Circuit

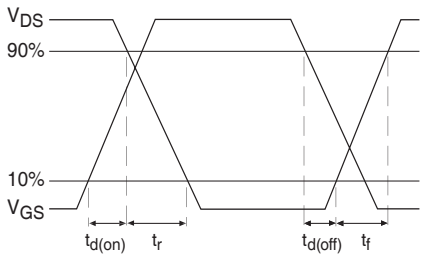


Fig 13b. Switching Time Waveforms

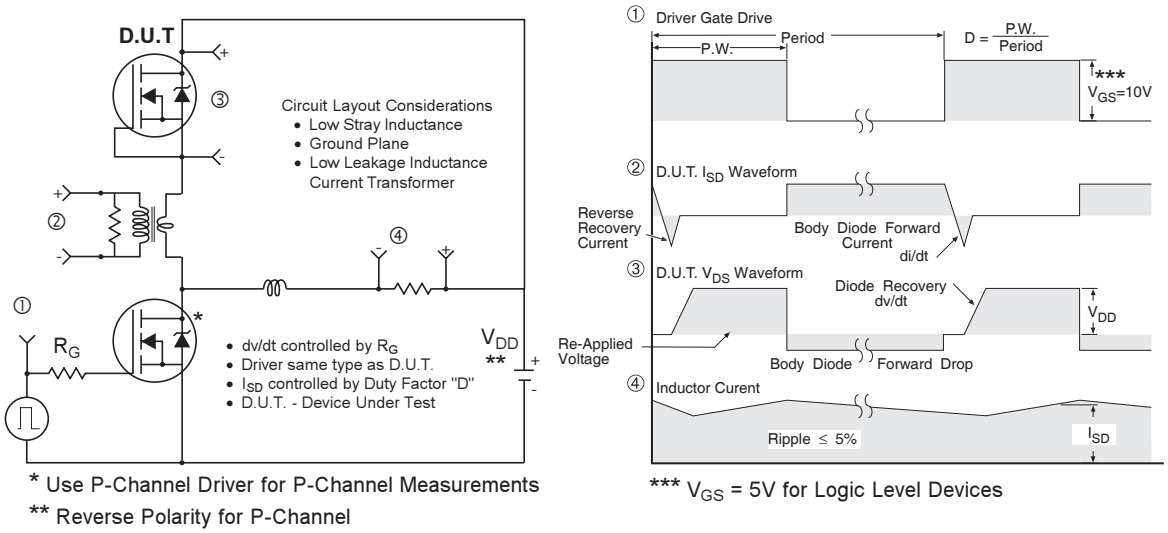


Fig 14. Diode Reverse Recovery Test Circuit for HEXFET® Power MOSFETs

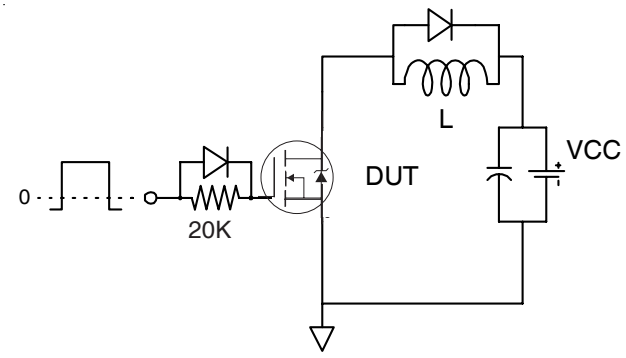


Fig 15. Gate Charge Test Circuit

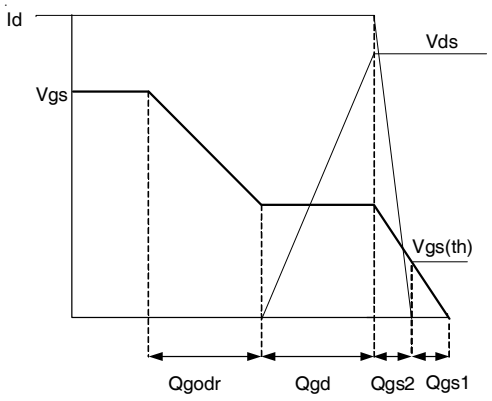
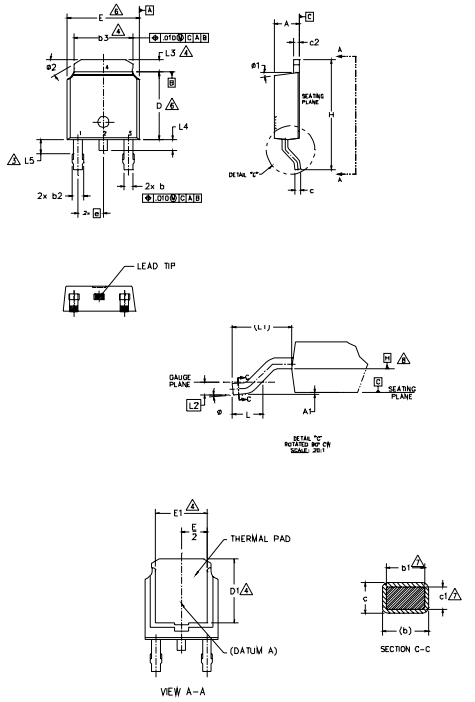


Fig 16. Gate Charge Waveform

D-Pak (TO-252AA) Package Outline

Dimensions are shown in millimeters (inches)



NOTES:

1.– DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994

2.– DIMENSION ARE SHOWN IN INCHES [MILLIMETERS].

3– LEAD DIMENSION UNCONTROLLED IN L5.

4– DIMENSION D1, E1, L3 & b3 ESTABLISH A MINIMUM MOUNTING SURFACE FOR THERMAL PAD.

5.– SECTION C–C DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN .005 AND 0.10 [0.13 AND 0.25] FROM THE LEAD TIP.

6– DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED .005 [0.13] PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTMOST EXTREMES OF THE PLASTIC BODY.

7– DIMENSION b1 & c1 APPLIED TO BASE METAL ONLY.

8– DATUM A & B TO BE DETERMINED AT DATUM PLANE H.

9.– OUTLINE CONFORMS TO JEDEC OUTLINE TO-252AA.

SYMBOL	DIMENSIONS				NOTES
	MILLIMETERS		INCHES		
	MIN.	MAX.	MIN.	MAX.	
A	2.18	2.39	.086	.094	
A1	–	0.13	–	.005	
b	0.64	0.89	.025	.035	
b1	0.65	0.79	.025	.031	7
b2	0.76	1.14	.030	.045	
b3	4.95	5.46	.195	.215	4
c	0.46	0.61	.018	.024	
c1	0.41	0.56	.016	.022	7
c2	0.46	0.89	.018	.035	
D	5.97	6.22	.235	.245	6
D1	5.21	–	.205	–	4
E	6.35	6.73	.250	.265	6
E1	4.32	–	.170	–	4
e	2.29 BSC		.090 BSC		
H	9.40	10.41	.370	.410	
L	1.40	1.78	.055	.070	
L1	2.74 BSC		.108 REF.		
L2	0.51 BSC		.020 BSC		
L3	0.89	1.27	.035	.050	4
L4	–	1.02	–	.040	
L5	1.14	1.52	.045	.060	3
ø	0°	10°	0°	10°	
ø1	0°	15°	0°	15°	
ø2	25°	35°	25°	35°	

LEAD ASSIGNMENTS

HEXFET

1.– GATE
2.– DRAIN
3.– SOURCE
4.– DRAIN

IGBT & CoPAK

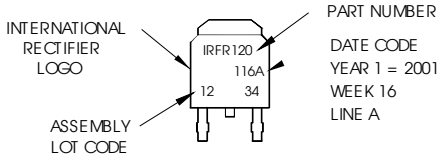
1.– GATE
2.– COLLECTOR
3.– EMITTER
4.– COLLECTOR

D-Pak (TO-252AA) Part Marking Information

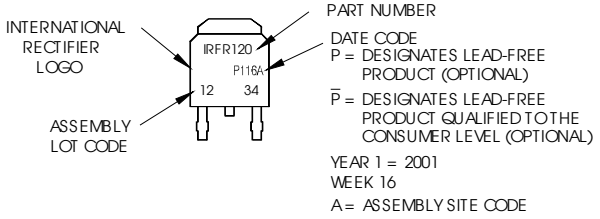
EXAMPLE: THIS IS AN IRFR120
WITH ASSEMBLY
LOT CODE 1234
ASSEMBLED ON WW 16, 2001
IN THE ASSEMBLY LINE "A"

Note: "P" in assembly line position indicates "Lead-Free"

"$\bar{P}$" in assembly line position indicates "Lead-Free" qualification to the consumer-level

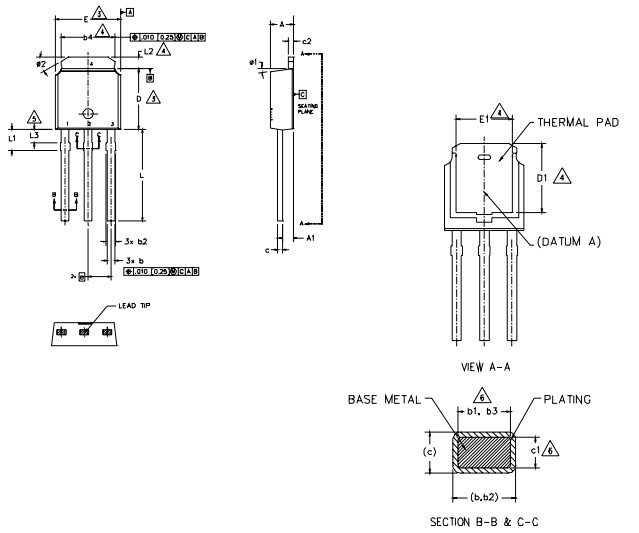


OR



I-Pak (TO-251AA) Package Outline

Dimensions are shown in millimeters (inches)



NOTES:

1.- DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994

2.- DIMENSION ARE SHOWN IN INCHES [MILLIMETERS].

3. DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED .005 [0.13] PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTMOST EXTREMES OF THE PLASTIC BODY.

4. THERMAL PAD CONTOUR OPTION WITHIN DIMENSION b4, L2, E1 & D1.

5. LEAD DIMENSION UNCONTROLLED IN L3.

6. DIMENSION b1, b3 & c1 APPLY TO BASE METAL ONLY.

7.- OUTLINE CONFORMS TO JEDEC OUTLINE TO-251AA (Date 06/02).

8.- CONTROLLING DIMENSION : INCHES.

SYMBOL	DIMENSIONS				NOTES
	MILLIMETERS		INCHES		
	MIN.	MAX.	MIN.	MAX.	
A	2.18	2.39	.086	.094	
A1	0.89	1.14	.035	.045	
b	0.64	0.89	.025	.035	
b1	0.65	0.79	.025	.031	6
b2	0.76	1.14	.030	.045	
b3	0.76	1.04	.030	.041	6
b4	4.95	5.46	.195	.215	4
c	0.46	0.61	.018	.024	
c1	0.41	0.56	.016	.022	6
c2	0.46	0.89	.018	.035	
D	5.97	6.22	.235	.245	3
D1	5.21	–	.205	–	4
E	6.35	6.73	.250	.265	3
E1	4.32	–	.170	–	4
e	2.29 BSC		.090 BSC		
L	8.89	9.65	.350	.380	
L1	1.91	2.29	.045	.090	
L2	0.89	1.27	.035	.050	4
L3	1.14	1.52	.045	.060	5
ø1	0°	15°	0°	15°	
ø2	25°	35°	25°	35°	

LEAD ASSIGNMENTS

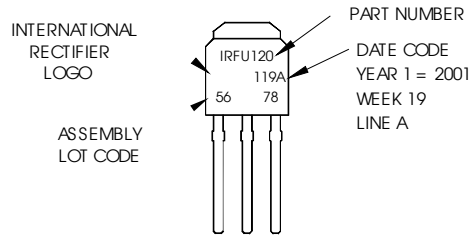
HEXFET

1.- GATE
2.- DRAIN
3.- SOURCE
4.- DRAIN

I-Pak (TO-251AA) Part Marking Information

EXAMPLE: THIS IS AN IRFU120
WITH ASSEMBLY
LOT CODE 5678
ASSEMBLED ON WW 19, 2001
IN THE ASSEMBLY LINE "A"

Note: "P" in assembly line position
indicates Lead-Free"



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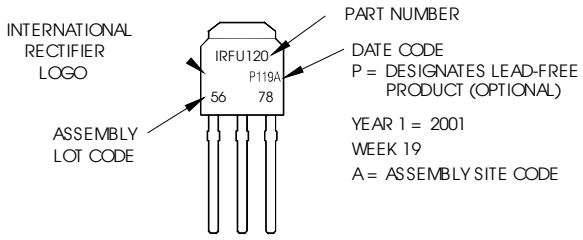
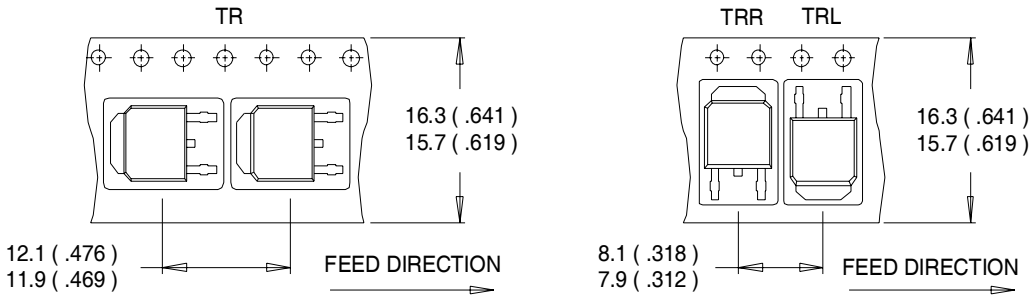
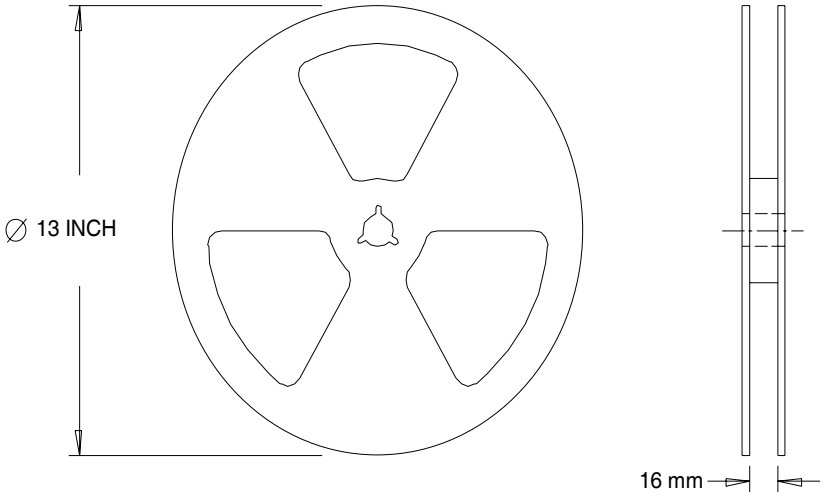


D-Pak (TO-252AA) Tape & Reel Information

Dimensions are shown in millimeters (inches)



NOTES :
1. CONTROLLING DIMENSION : MILLIMETER.
2. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).
3. OUTLINE CONFORMS TO EIA-481 & EIA-541.



NOTES :
1. OUTLINE CONFORMS TO EIA-481.